

Bill of Materials

TI DESIGNS

TIDA-00325 DLP Board (2513848)

Item	Qty	Reference	Value	Part Description	Manufacturer	Manufacturer Part Number	Alternate Part	PCB Footprint	Note
1	2	C1,C2	9pF	CAP CER 9PF 50V NPO 0402	TDK	CGJ2B2COG1H090D050B		402	
2	3	C3,C4,C7	10uF	CAP CER 10UF 10V 20% X5R 0603	TDK	C1608X5R1A106M080AC		603	
3	3	C5,C9,C10	0.22uF	CAP CER 0.22UF 25V 10% X5R 0402	TDK	C1005X5R1E224K050BC		402	
4	1	C6	22uF	CAP CER 22UF 10V 20% X5R 0603	TDK	C1608X5R1A226M080AC		603	
5	5	C8,C24,C39,C52,C53	1uF	CAP CER 1.0UF 10V X5R 0402	TDK	C1005X5R1A105M		402	
6	28	C11,C18,C19,C20,C23,C25	0.1uF	CAP CER .1UF 16V X7R 0402	TDK	C1005X7R1C104K050BC		0402_AVXA	
7	4	C12,C13,C15,C54	22uF	CAP CER 22UF 6.3V 20% X5R 0603	TDK	C1608X5R0J226M		603	
8	1	C14	2.2uF	CAP CER 2.2UF 6.3V X5R 0402	TDK	C1005X5R0J225M		402	
9	1	C16	1uF	CAP CER 1.0UF 16V X5R 0402	TDK	C1005X5R1C105K		402	
10	1	C17	4.7uF	CAP CER 4.7UF 6.3V 20% X5R 0402	TDK	C1005X5R0J475M		402	
11	2	C21,C22	0.01uF	CAP CER 10000PF 16V X7R 10% 0402	TDK	C1005X7R1C103K		402	
12	3	C49,C50,C51	0.1uF	CAP CER .10UF 25V X5R 0402	Taiyo Yuden	TMK105BJ104KV-F		402	
13	1	D1	PMEG4002EL	SCHOTTKY RECT 40V 0.2A SOD882	NXP Semiconductors	PMEG4002EL,315		SOD882	
14	2	F1,F2	BLM15PD800SN1D	FERRITE CHIP 80 OHM 1500MA 0402	Murata	BLM15PD800SN1D		BLM15P	
15	1	J1	AXT550124	CONN SOCKET F4S .4MM 50POS SMD	Panasonic	AXT550124		Panasonic_AXT550124_counter_clkwise_pinout	
16	1	J2	S4B-EH	CONN HEADER EH SIDE 4POS 2.5MM	JST	S4B-EH(LF)(SN)		JST_S4B-EH	
17	3	J3,J4,J5	B3B-ZR	CONN HEADER ZH TOP 3POS 1.5MM	JST	B3B-ZR-SM4-TF(LF)(SN)(P)		JST_B3B-ZR-SM4-TF_LF_SN_P	
18	1	J6	QSH-030-01-L-D-A	CONN RCPT HI-SPD .5MM 60POS DL (stacking ht 5mm)	Samtec	QSH-030-01-L-D-A		Samtec_QSH-030-xx-x-D-A	
19	1	L1	10uH	INDUCTOR 10UH 20% 0805 SMD	Taiyo Yuden	CBL2012T100M		805	
20	1	L2	2.2uH	INDUCTOR SHIELD PWR 2.2UH SMD Irms-4.76A Isat-7.06A	Cooper Bussmann	DR74-2R2-R		CooperBussmann_DR74	
21	1	L3	2.2uH	INDUCTOR 2.2UH 20% 1300MA	Murata	LQM2HPN2R2MG0L		1008_2p5mmx2mm	
22	1	RT1	100k	THERMISTOR 100K OHM NTC	Murata	NCP15WF104F03RC		402	
23	1	R1	100	RES 100 OHM 1/10W 1% 0402	Panasonic	ERJ-2RKF1000X		402	
24	1	R2	953k	RES 953K OHM 1/10W 1% 0402	Panasonic	ERJ-2RKF9533X		402	
25	2	R3,R4	43	RES 43 OHM 1/20W 5% 0201 SMD	Panasonic	ERJ-1GEJ430C		201	
26	7	R5,R8,R9,R14,R25,R26,R3	100k	RES 100K OHM 1/10W 1% 0402	Panasonic	ERJ-2RKF1003X		402	
27	8	R6,R7,R10,R11,R12,R13,R	30.1	RES 30.1 OHM 1/16W 1% 0402	Panasonic	ERJ-2RKF30R1X		402	

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28	1	R15	0.039	RES 0.039 OHM 1/4W 1% 0603	Rohm	UCR03EWPFSR039		603	
29	4	R16,R18,R23,R27	10k		Panasonic	ERJ-2RKF1002X		402	
30	1	R17	300	RES 300 OHM 1/10W 1% 0402	Panasonic	ERJ-2RKF3000X		402	
31	3	R19,R20,R22	30.0k	RES 30.0K OHM 1/10W 1% 0402	Panasonic	ERJ-2RKF3002X		402	
32	1	R21	0	RES 0.0 OHM 1/16W 0402 SMD	Panasonic	ERJ-2GE0R00X		402	
33	1	R24	7.87k	RES 7.87K OHM 1/10W 1% 0402	Panasonic	ERJ-2RKF7871X		402	
34	4	TPGND1,TPGND2,TPGND3	TP_BLK	TEST POINT PC MINI .040inD	Keystone	5001		KEYSTONE_TP_MINIATURE	
35	1	U1	DLPC3435		Texas Instruments	DLPC3435ZEZ		DLPC3435_13mmx13mm_VFBGA_201balls	
36	1	U2	DLPA2005	Power & LED Driver IC for DLP	Texas Instruments	DLPA2005ERSLT		DLPA2005_RSL_S-PQFP-N48_QFN48	
37	1	X1	24MHz	Type NX2016SA, 24MHz	KDS	DSX211G-24.000M-6pF-		NDK_EXS00A-CS05733	

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